

DNP
FID1

DNP
FID2

DNP
FID3

PCB Number: TIDA-00534
PCB Rev: E1

PCB
LOGO
Texas Instruments

PCB
LOGO
Pb-Free Symbol

Label Table

Variant	Label Text
001	TIDA-00534

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

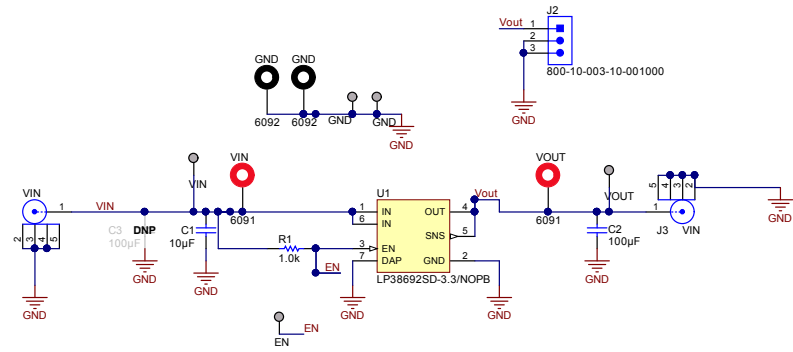
Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



Orderable: N/A	Designed for: Public Release	Mod. Date: 8/3/2015
TID #: 00534	Project Title: Power Management Ref. Design for CC3200	
Number: TIDA-00534 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: TIDA-00534_Sheet1_SchDoc	Size: B
Engineer: Antony Carvajales	Contact: http://www.ti.com/support	

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